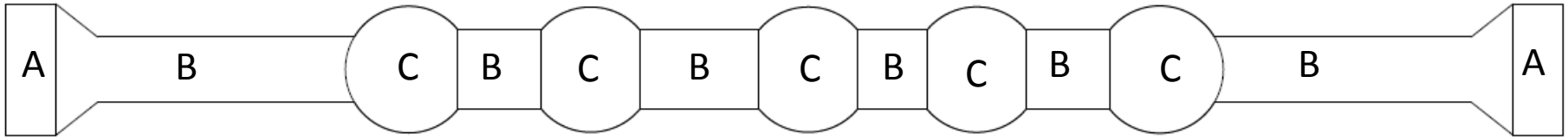
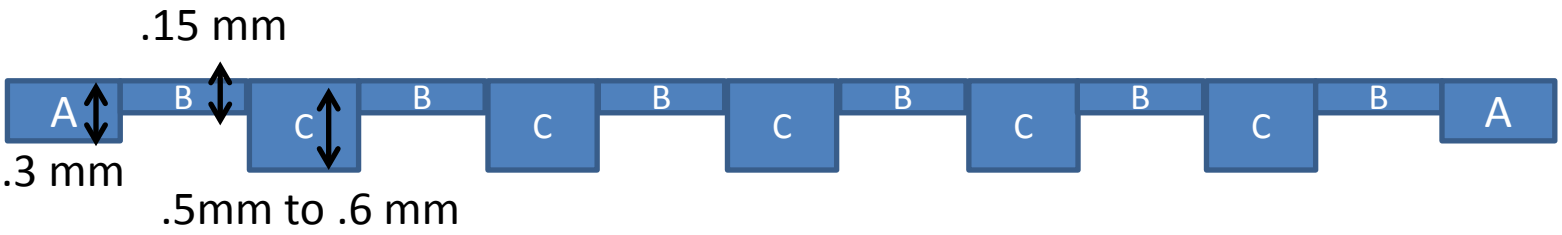


Regions A have to mate with connector MOLEX 52207-1033 a final thickness of .3 mm is required, then apply adhesive and stiffener to match this height
Regions B are without any stiffener applied, a final thickness between .15 and .2 mm is fine. Maybe to keep bending angles smaller I would make them .15
Regions C are areas where the connector is going to be soldered and then rigid PCB (as the smaller BGA one) are going to be mounted. I would keep these areas final thickness in a range of .5 mm min and .6 mm max. So stiffener to match this height has to be applied

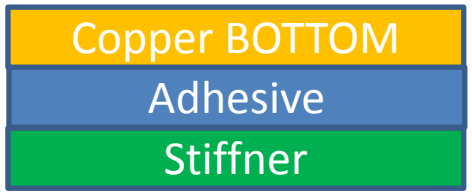
- Board Finishing I would consider ENIG
- White Silkscreen

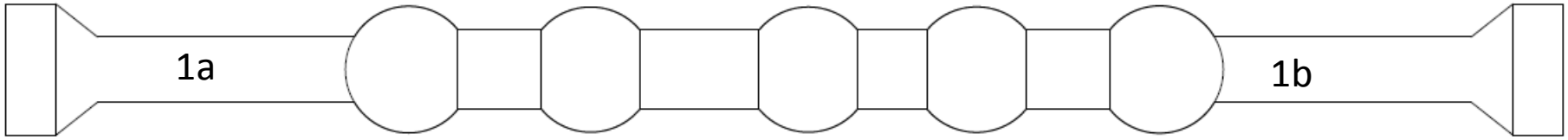

.15 mm
A
B
C
B
C
B
C
B
C
B
C
B
A
.3 mm
.5mm to .6 mm


Copper TOP
Adhesive
Polyimide

.

.


Copper BOTTOM
Adhesive
Stiffner



- Bending radios for all the sections is about (± 120 degrees) apart section 1a and 1b where there is no bending involved (just less then 10 degrees)

We don’t want to increase stiffener in the last regions as they have to mate .3 mm of the mating connector. Just put the stiffener of the right width to mate it.